

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BYUNG SOO EUN	07/07/2010
RECEIVING PARTY DATA	
Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	SAN 136-1, AMI-RI, BUBAL-EUP, ICHEON-SI
City:	GYEONGGI-DO
State/Country:	REPUBLIC OF KOREA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12834135
CORRESPONDENCE DATA	
Fax Number: (312)427-6663 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 3124271300 Email: nicholas.kubacki@ladas.net Correspondent Name: RICHARD J. STREIT Address Line 1: LADAS & PARRY, 224 SOUTH MICHIGAN AVE. Address Line 4: CHICAGO, ILLINOIS 60604	
ATTORNEY DOCKET NUMBER:	CU-8385 BWH/HYNIX/NK
NAME OF SUBMITTER:	Brian W. Hameder
Total Attachments: 2 source=cu8385assign#page1.tif source=cu8385assign#page2.tif	

CH \$40.00 12834135

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PATENT
REEL: 024665 FRAME: 0205

UNITED STATES OF AMERICA
ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:

EUN, Byung Soo

#201, Samsung Villa, 412-374 Sillimbon-dong, Gwanak-gu, Seoul, Republic of Korea

hereby sell, assign and transfer to

ASSIGNEE:

Hynix Semiconductor Inc.

San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Republic of Korea

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the Application entitled

**METHOD FOR FABRICATING STORAGE NODE ELECTRODE IN
SEMICONDUCTOR DEVICE**

which application was

☒ (a) executed on event date herewith

☐ (b) filed as Serial No. _____ on _____

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and



deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

July 7, 2010

Date

EUN Byung Soo

INVENTOR EUN, Byung Soo

0699P/1 (U.S. rights)

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